



MICROCHIP MCP6401/1R/1U/2/4

1 MHz, 45 μ A Op Amps

Features

- Low Quiescent Current: 45 μ A (typical)
- Gain Bandwidth Product: 1 MHz (typical)
- Rail-to-Rail Input and Output
- Supply Voltage Range: 1.8V to 6.0V
- Unity Gain Stable
- Extended Temperature Range: -40°C to +125°C
- No Phase Reversal

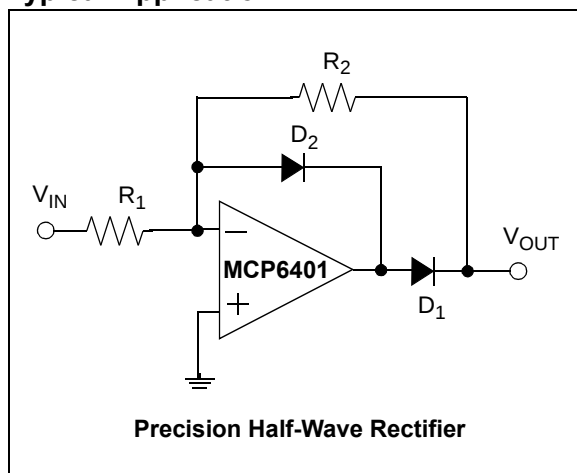
Applications

- Portable Equipment
- Battery Powered System
- Medical Instrumentation
- Data Acquisition Equipment
- Sensor Conditioning
- Supply Current Sensing
- Analog Active Filters

Design Aids

- SPICE Macro Models
- FilterLab[®] Software
- Mindi[™] Circuit Designer and Simulator
- Microchip Advanced Part Selector (MAPS)
- Analog Demonstration and Evaluation Boards
- Application Notes

Typical Application

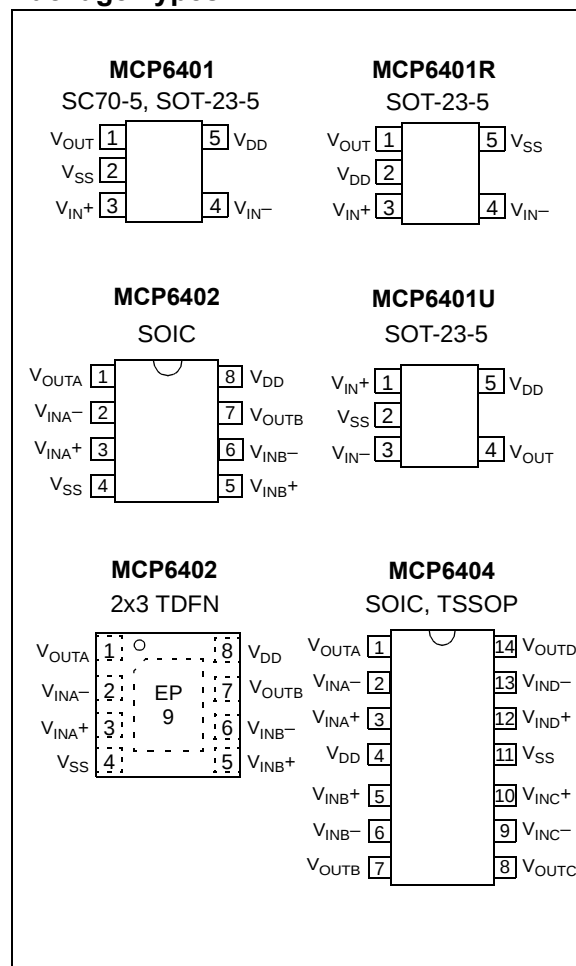


Description

The Microchip Technology Inc. MCP6401/1R/1U/2/4 family of operational amplifiers (op amps) has low quiescent current (45 μ A, typical) and rail-to-rail input and output operation. This family is unity gain stable and has a gain bandwidth product of 1 MHz (typical). These devices operate with a single supply voltage as low as 1.8V. These features make the family of op amps well suited for single-supply, battery-powered applications.

The MCP6401/1R/1U/2/4 family is designed with Microchip's advanced CMOS process and offered in single packages. All devices are available in the extended temperature range, with a power supply range of 1.8V to 6.0V.

Package Types



MCP6401/1R/1U/2/4

NOTES:

1.0 ELECTRICAL CHARACTERISTICS

1.1 Absolute Maximum Ratings †

$V_{DD} - V_{SS}$	7.0V
Current at Input Pins	±2 mA
Analog Inputs (V_{IN+} , V_{IN-})††	$V_{SS} - 1.0V$ to $V_{DD} + 1.0V$
All Other Inputs and Outputs	$V_{SS} - 0.3V$ to $V_{DD} + 0.3V$
Difference Input Voltage	$ V_{DD} - V_{SS} $
Output Short-Circuit Current	Continuous
Current at Output and Supply Pins	±30 mA
Storage Temperature	-65°C to +150°C
Maximum Junction Temperature (T_J)	+150°C
ESD Protection on All Pins (HBM; MM)	≥ 4 kV; 300V

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

†† See Section 4.1.2 “Input Voltage Limits”

DC ELECTRICAL SPECIFICATIONS

Electrical Characteristics: Unless otherwise indicated, $V_{DD} = +1.8V$ to $+6.0V$, $V_{SS} = GND$, $T_A = +25^\circ C$, $V_{CM} = V_{DD}/2$, $V_{OUT} \gg V_{DD}/2$, $V_L = V_{DD}/2$ and $R_L = 100\text{ k}\Omega$ to V_L . (Refer to Figure 1-1).

Parameters	Sym	Min	Typ	Max	Units	Conditions
Input Offset						
Input Offset Voltage	V _{OS}	-4.5	—	+4.5	mV	V _{CM} = V _{SS}
Input Offset Drift with Temperature	ΔV _{OS} /ΔT _A	—	±2.0	—	μV/°C	T _A = -40°C to +125°C, V _{CM} = V _{SS}
Power Supply Rejection Ratio	PSRR	63	78	—	dB	V _{CM} = V _{SS}
Input Bias Current and Impedance						
Input Bias Current	I _B	—	±1.0	100	pA	T _A = +85°C T _A = +125°C
		—	30	—	pA	
		—	800	—	pA	
Input Offset Current	I _{OS}	—	±1.0	—	pA	
Common Mode Input Impedance	Z _{CM}	—	10 ¹³ 6	—	Ω pF	
Differential Input Impedance	Z _{DIFF}	—	10 ¹³ 6	—	Ω pF	
Common Mode						
Common Mode Input Voltage Range	V _{CMR}	V _{SS} -0.2	—	V _{DD} +0.2	V	V _{DD} = 1.8V, Note 1
		V _{SS} -0.3	—	V _{DD} +0.3	V	V _{DD} = 6.0V, Note 1
Common Mode Rejection Ratio	CMRR	56	71	—	dB	V _{CM} = -0.2V to 2.0V, V _{DD} = 1.8V
		63	78	—	dB	V _{CM} = -0.3V to 6.3V, V _{DD} = 6.0V
Open-Loop Gain						
DC Open-Loop Gain (Large Signal)	A _{OL}	90	110	—	dB	V _{OUT} = 0.3V to V _{DD} -0.3V V _{CM} = V _{SS}
Output						
Maximum Output Voltage Swing	V _{OL} , V _{OH}	V _{SS} +20	—	V _{DD} -20	mV	V _{DD} = 6.0V, R _L = 10 kΩ 0.5V input overdrive
Output Short-Circuit Current	I _{SC}	—	±5	—	mA	V _{DD} = 1.8V
		—	±15	—	mA	V _{DD} = 6.0V
Power Supply						
Supply Voltage	V _{DD}	1.8	—	6.0	V	
Quiescent Current per Amplifier	I _Q	20	45	70	μA	I _O = 0, V _{DD} = 5.0V V _{CM} = 0.2V _{DD}

Note 1: Figure 2-11 shows how V_{CMR} changes across temperature.

MCP6401/1R/1U/2/4

AC ELECTRICAL SPECIFICATIONS

Electrical Characteristics: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$. (Refer to Figure 1-1).

Parameters	Sym	Min	Typ	Max	Units	Conditions
AC Response						
Gain Bandwidth Product	GBWP	—	1	—	MHz	
Phase Margin	PM	—	65	—	°	$G = +1\text{ V/V}$
Slew Rate	SR	—	0.5	—	$\text{V}/\mu\text{s}$	
Noise						
Input Noise Voltage	E_{ni}	—	3.6	—	$\mu\text{Vp-p}$	$f = 0.1\text{ Hz to }10\text{ Hz}$
Input Noise Voltage Density	e_{ni}	—	28	—	$\text{nV}/\sqrt{\text{Hz}}$	$f = 1\text{ kHz}$
Input Noise Current Density	i_{ni}	—	0.6	—	$\text{fA}/\sqrt{\text{Hz}}$	$f = 1\text{ kHz}$

TEMPERATURE SPECIFICATIONS

Electrical Characteristics: Unless otherwise indicated, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$ and $V_{SS} = \text{GND}$.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Operating Temperature Range	T_A	-40	—	+125	$^\circ\text{C}$	Note 1
Storage Temperature Range	T_A	-65	—	+150	$^\circ\text{C}$	
Thermal Package Resistances						
Thermal Resistance, 5L-SC70	θ_{JA}	—	331	—	$^\circ\text{C}/\text{W}$	
Thermal Resistance, 5L-SOT-23	θ_{JA}	—	220.7	—	$^\circ\text{C}/\text{W}$	
Thermal Resistance, 8L-SOIC	θ_{JA}	—	149.5	—	$^\circ\text{C}/\text{W}$	
Thermal Resistance, 8L-2x3 TDFN	θ_{JA}	—	41	—	$^\circ\text{C}/\text{W}$	
Thermal Resistance, 14L-SOIC	θ_{JA}	—	95.3	—	$^\circ\text{C}/\text{W}$	
Thermal Resistance, 14L-TSSOP	θ_{JA}	—	100	—	$^\circ\text{C}/\text{W}$	

Note 1: The internal junction temperature (T_J) must not exceed the absolute maximum specification of $+150^\circ\text{C}$.

1.2 Test Circuits

The circuit used for most DC and AC tests is shown in Figure 1-1. This circuit can independently set V_{CM} and V_{OUT} ; see Equation 1-1. Note that V_{CM} is not the circuit's Common Mode voltage ($(V_P + V_M)/2$), and that V_{OST} includes V_{OS} plus the effects (on the input offset error, V_{OST}) of temperature, CMRR, PSRR and A_{OL} .

EQUATION 1-1:

$$G_{DM} = R_F/R_G$$

$$V_{CM} = (V_P + V_{DD}/2)/2$$

$$V_{OST} = V_{IN-} - V_{IN+}$$

$$V_{OUT} = (V_{DD}/2) + (V_P - V_M) + V_{OST}(1 + G_{DM})$$

Where:

$$G_{DM} = \text{Differential Mode Gain} \quad (\text{V/V})$$

$$V_{CM} = \text{Op Amp's Common Mode Input Voltage} \quad (\text{V})$$

$$V_{OST} = \text{Op Amp's Total Input Offset Voltage} \quad (\text{mV})$$

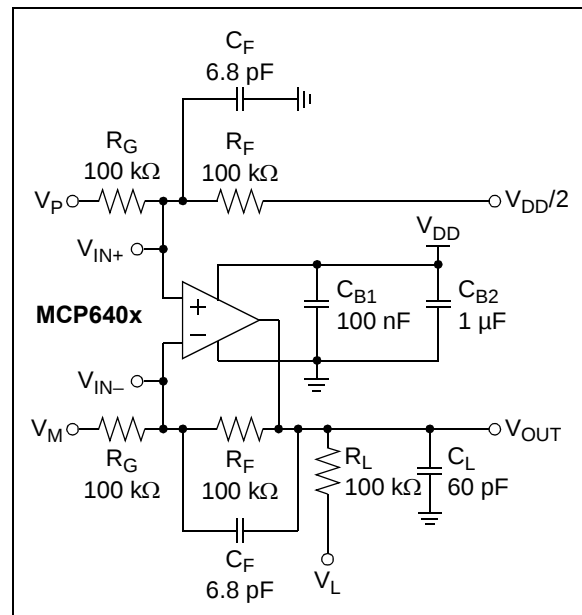


FIGURE 1-1: AC and DC Test Circuit for Most Specifications.

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$.

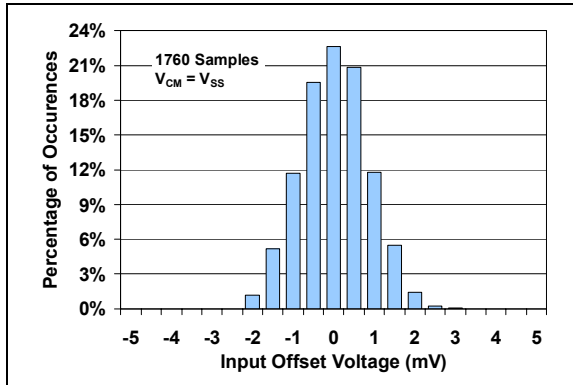


FIGURE 2-1: Input Offset Voltage.

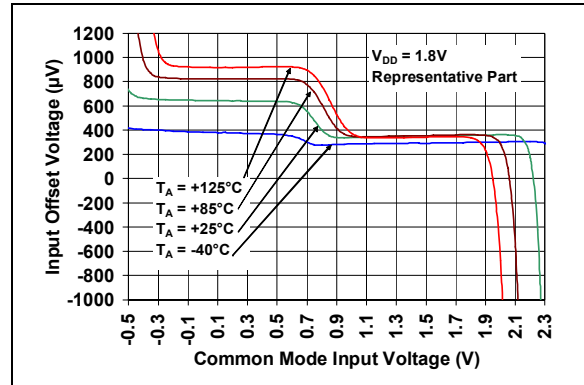


FIGURE 2-4: Input Offset Voltage vs. Common Mode Input Voltage with $V_{DD} = 1.8\text{V}$.

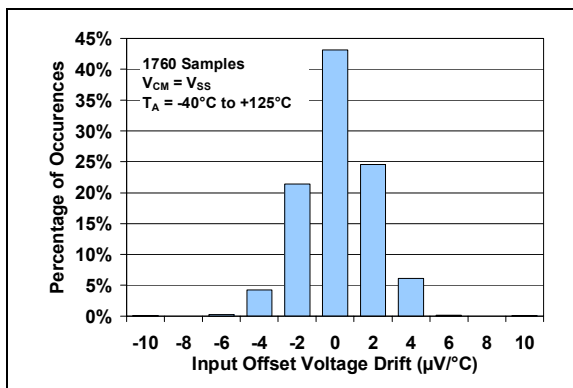


FIGURE 2-2: Input Offset Voltage Drift.

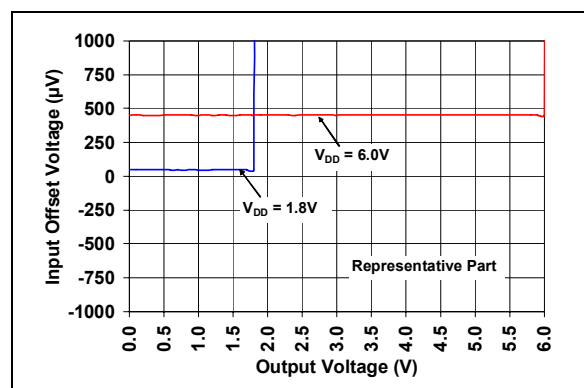


FIGURE 2-5: Input Offset Voltage vs. Output Voltage.

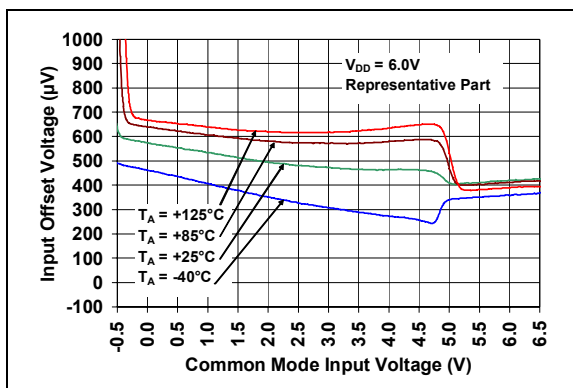


FIGURE 2-3: Input Offset Voltage vs. Common Mode Input Voltage with $V_{DD} = 6.0\text{V}$.

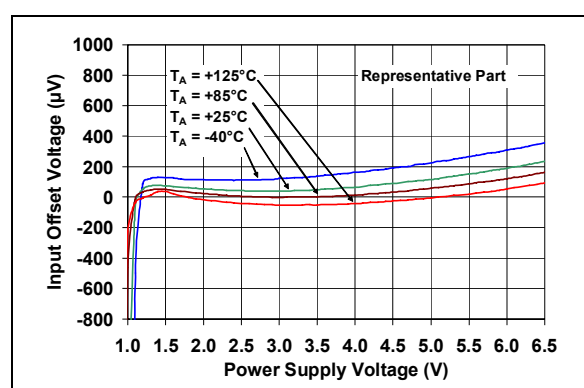


FIGURE 2-6: Input Offset Voltage vs. Power Supply Voltage.

MCP6401/1R/1U/2/4

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$.

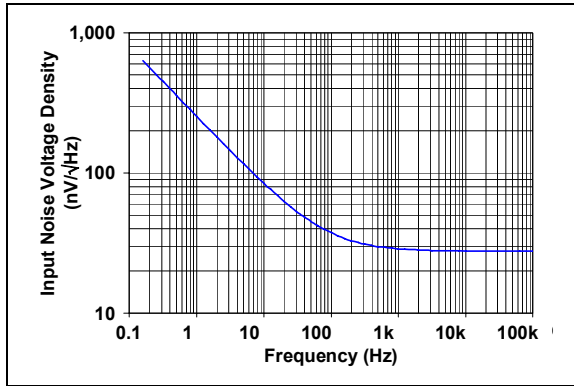


FIGURE 2-7: Input Noise Voltage Density vs. Frequency.

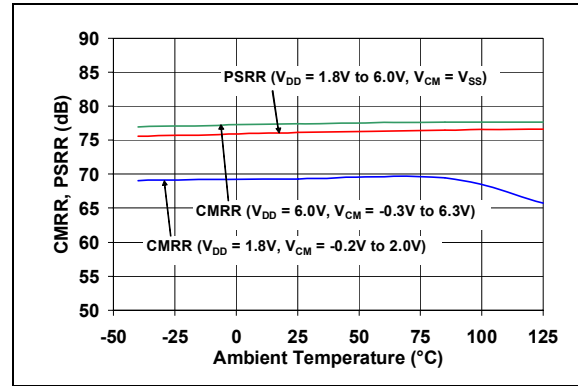


FIGURE 2-10: CMRR, PSRR vs. Ambient Temperature.

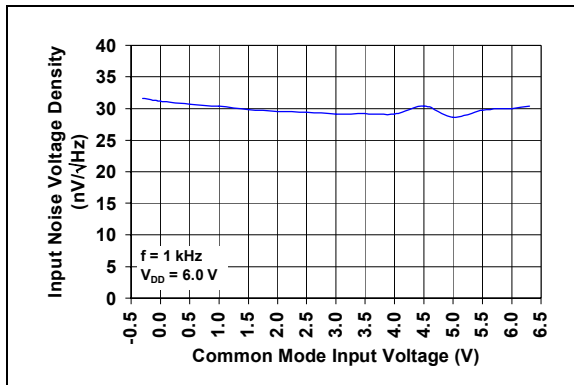


FIGURE 2-8: Input Noise Voltage Density vs. Common Mode Input Voltage.

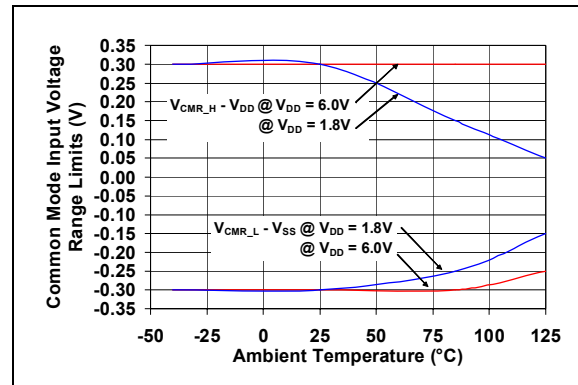


FIGURE 2-11: Common Mode Input Voltage Range Limits vs. Ambient Temperature.

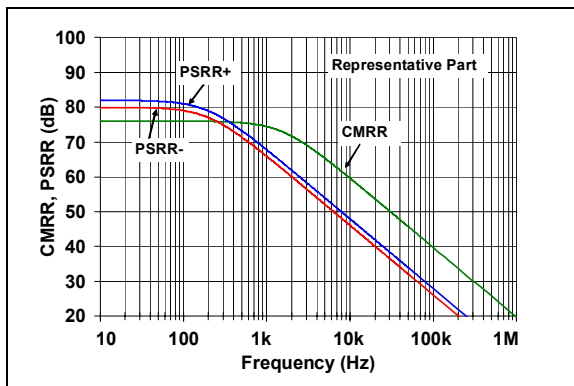


FIGURE 2-9: CMRR, PSRR vs. Frequency.

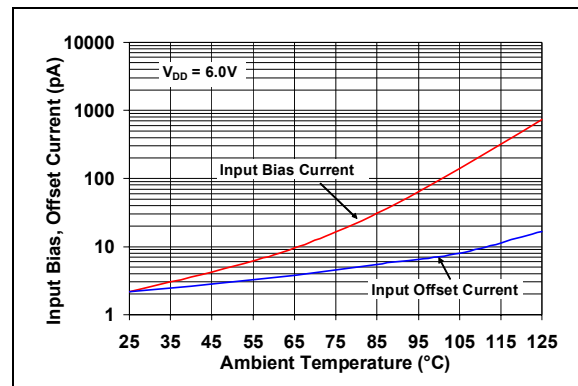


FIGURE 2-12: Input Bias, Offset Current vs. Ambient Temperature.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$.

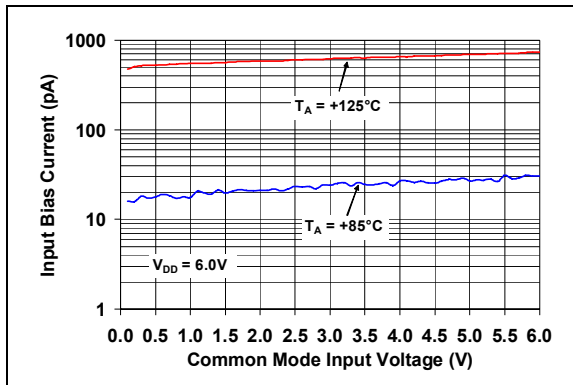


FIGURE 2-13: Input Bias Current vs. Common Mode Input Voltage.

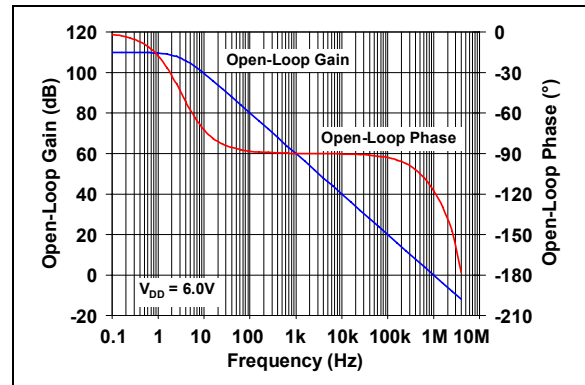


FIGURE 2-16: Open-Loop Gain, Phase vs. Frequency.

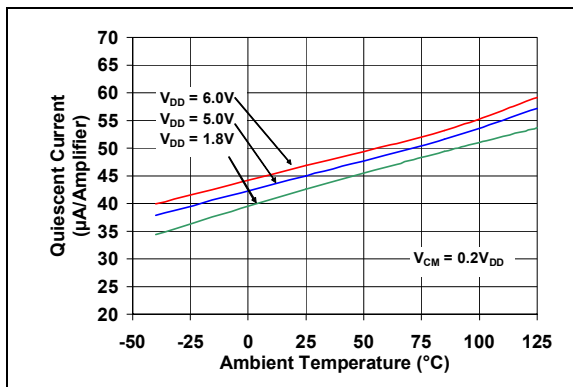


FIGURE 2-14: Quiescent Current vs. Ambient Temperature.

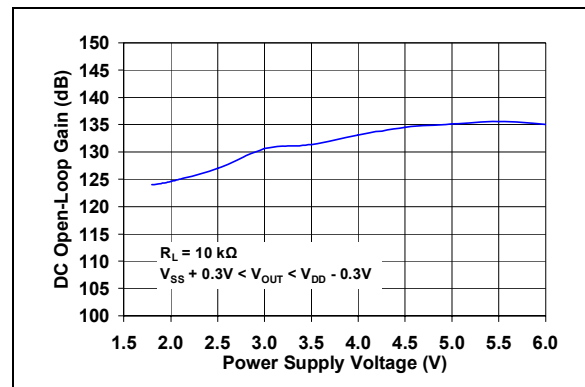


FIGURE 2-17: DC Open-Loop Gain vs. Power Supply Voltage.

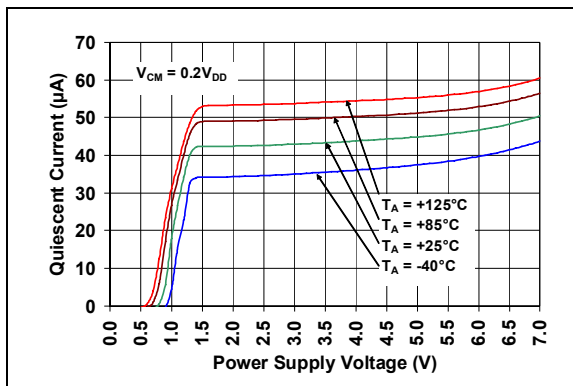


FIGURE 2-15: Quiescent Current vs. Power Supply Voltage.

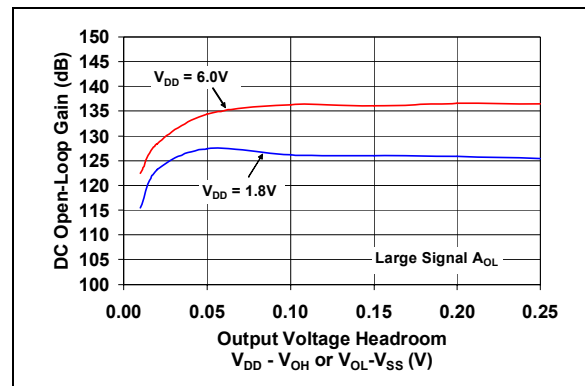


FIGURE 2-18: DC Open-Loop Gain vs. Output Voltage Headroom.

MCP6401/1R/1U/2/4

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$.

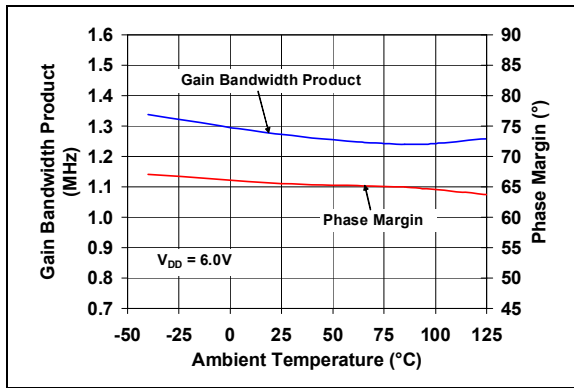


FIGURE 2-19: Gain Bandwidth Product, Phase Margin vs. Ambient Temperature.

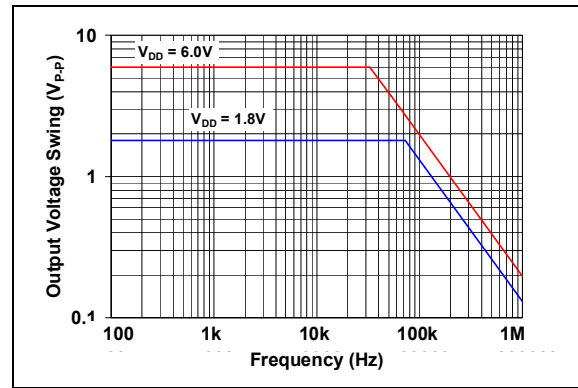


FIGURE 2-22: Output Voltage Swing vs. Frequency.

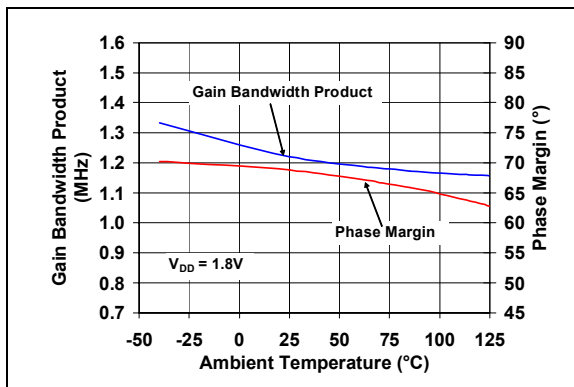


FIGURE 2-20: Gain Bandwidth Product, Phase Margin vs. Ambient Temperature.

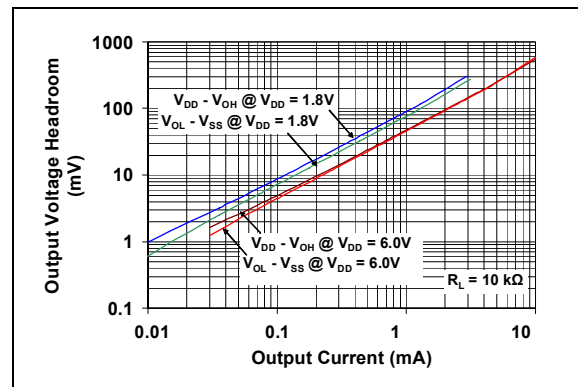


FIGURE 2-23: Output Voltage Headroom vs. Output Current.

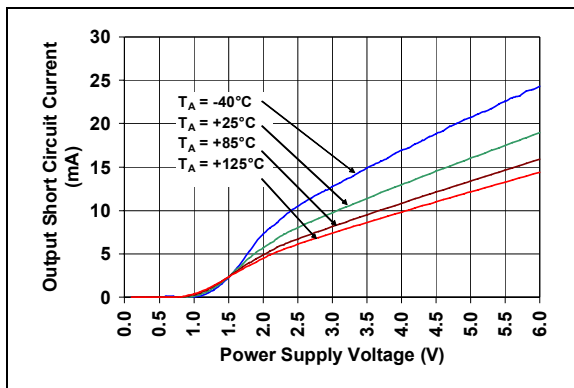


FIGURE 2-21: Output Short Circuit Current vs. Power Supply Voltage.

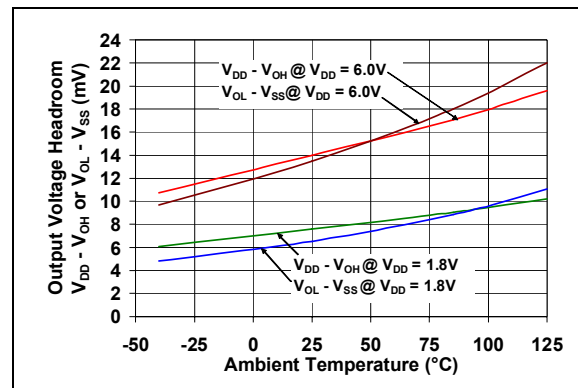


FIGURE 2-24: Output Voltage Headroom vs. Ambient Temperature.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$.

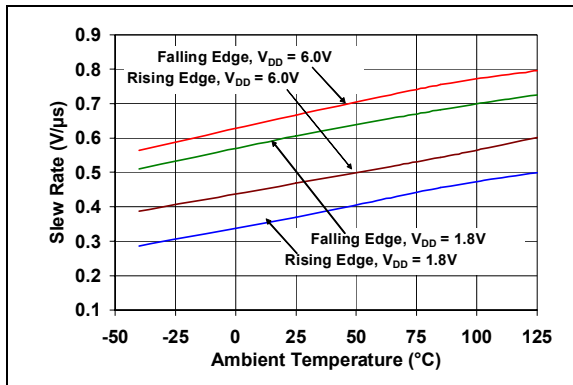


FIGURE 2-25: Slew Rate vs. Ambient Temperature.

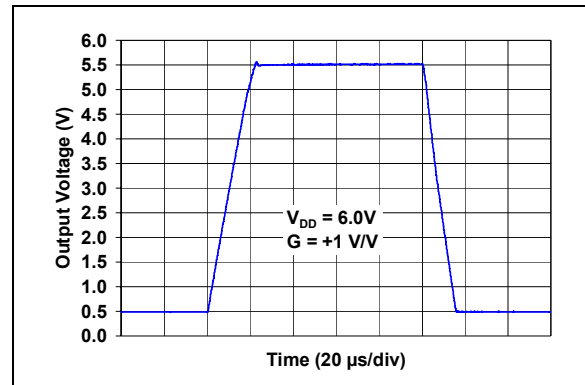


FIGURE 2-28: Large Signal Non-Inverting Pulse Response.

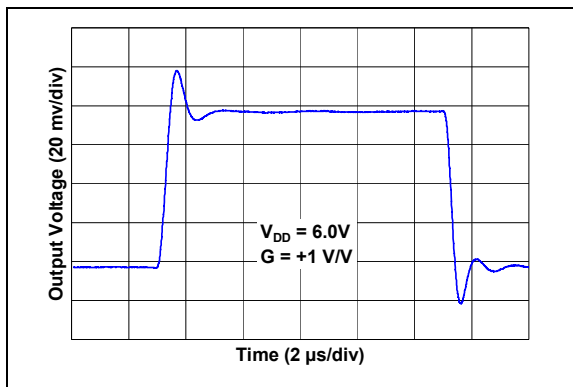


FIGURE 2-26: Small Signal Non-Inverting Pulse Response.

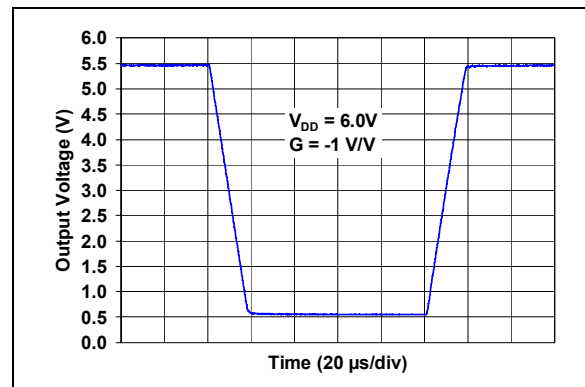


FIGURE 2-29: Large Signal Inverting Pulse Response.

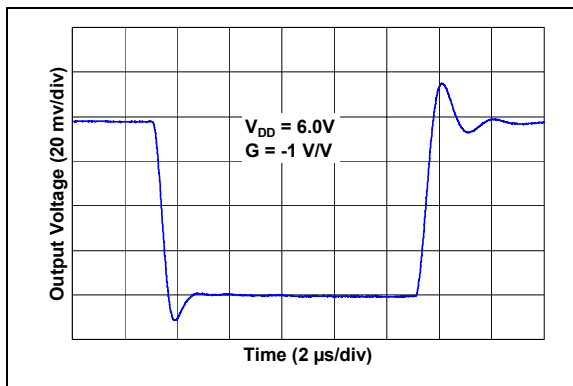


FIGURE 2-27: Small Signal Inverting Pulse Response.

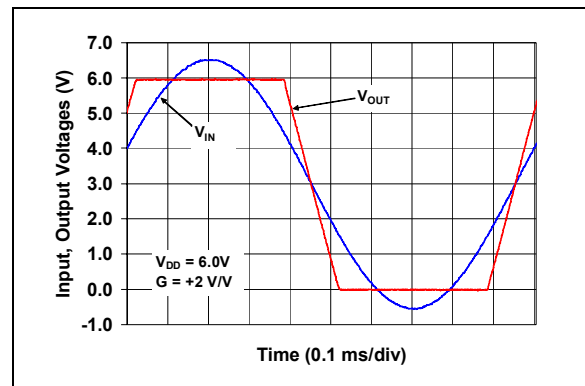


FIGURE 2-30: The MCP6401/1R/1U/2/4 Shows No Phase Reversal.

MCP6401/1R/1U/2/4

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$, $V_{DD} = +1.8\text{V}$ to $+6.0\text{V}$, $V_{SS} = \text{GND}$, $V_{CM} = V_{DD}/2$, $V_{OUT} \approx V_{DD}/2$, $V_L = V_{DD}/2$, $R_L = 100\text{ k}\Omega$ to V_L and $C_L = 60\text{ pF}$.

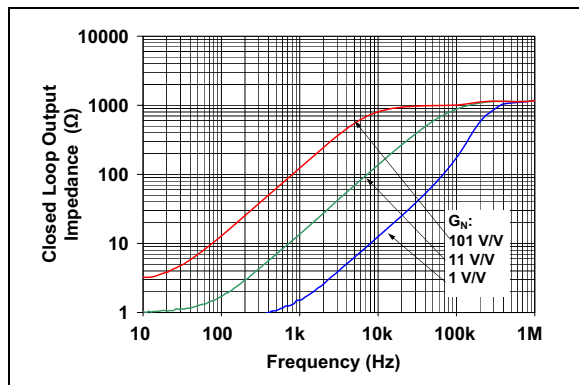


FIGURE 2-31: Closed Loop Output Impedance vs. Frequency.

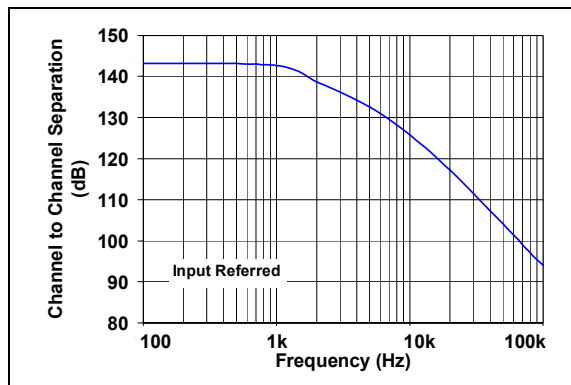


FIGURE 2-33: Channel-to-Channel Separation vs. Frequency (MCP6402/4 only).

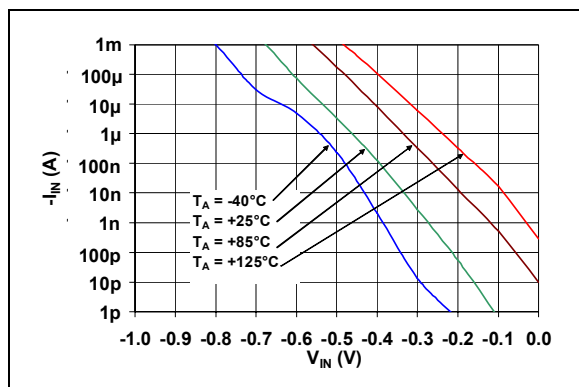


FIGURE 2-32: Measured Input Current vs. Input Voltage (below V_{SS}).

3.0 PIN DESCRIPTIONS

Descriptions of the pins are listed in [Table 3-1](#).

TABLE 3-1: PIN FUNCTION TABLE

MCP6401	MCP6401R	MCP6401U	MCP6402		MCP6404	Symbol	Description
SC70-5, SOT-23-5	SOT-23-5	SOT-23-5	SOIC	2x3 TDFN	SOIC, TSSOP		
1	1	4	1	1	1	V_{OUT}, V_{OUTA}	Analog Output (op amp A)
4	4	3	2	2	2	V_{IN-}, V_{INA-}	Inverting Input (op amp A)
3	3	1	3	3	3	V_{IN+}, V_{INA+}	Non-inverting Input (op amp A)
5	2	5	8	8	4	V_{DD}	Positive Power Supply
—	—	—	5	5	5	V_{INB+}	Non-inverting Input (op amp B)
—	—	—	6	6	6	V_{INB-}	Inverting Input (op amp B)
—	—	—	7	7	7	V_{OUTB}	Analog Output (op amp B)
—	—	—	—	—	8	V_{OUTC}	Analog Output (op amp C)
—	—	—	—	—	9	V_{INC-}	Inverting Input (op amp C)
—	—	—	—	—	10	V_{INC+}	Non-inverting Input (op amp C)
2	5	2	4	4	11	V_{SS}	Negative Power Supply
—	—	—	—	—	12	V_{IND+}	Non-inverting Input (op amp D)
—	—	—	—	—	13	V_{IND-}	Inverting Input (op amp D)
—	—	—	—	—	14	V_{OUTD}	Analog Output (op amp D)
—	—	—	—	9	—	EP	Exposed Thermal Pad (EP); must be connected to VSS.

3.1 Analog Output (V_{OUT})

The output pin is low-impedance voltage source.

3.2 Analog Inputs (V_{IN+} , V_{IN-})

The non-inverting and inverting inputs are high-impedance CMOS inputs with low bias currents.

3.3 Power Supply Pin (V_{DD} , V_{SS})

The positive power supply (V_{DD}) is 1.8V to 6.0V higher than the negative power supply (V_{SS}). For normal operation, the other pins are at voltages between V_{SS} and V_{DD} .

Typically, these parts are used in a single (positive) supply configuration. In this case, V_{SS} is connected to ground and V_{DD} is connected to the supply. V_{DD} will need bypass capacitors.

MCP6401/1R/1U/2/4

NOTES:

4.0 APPLICATION INFORMATION

The MCP6401/1R/1U/2/4 family of op amps is manufactured using Microchip's state-of-the-art CMOS process and is specifically designed for low-power, high precision applications.

4.1 Rail-to-Rail Input

4.1.1 PHASE REVERSAL

The MCP6401/1R/1U/2/4 op amps are designed to prevent phase reversal when the input pins exceed the supply voltages. Figure 2-30 shows the input voltage exceeding the supply voltage with no phase reversal.

4.1.2 INPUT VOLTAGE LIMITS

In order to prevent damage and/or improper operation of these amplifiers, the circuit must limit the voltages at the input pins (see Section 1.1 "Absolute Maximum Ratings †").

The ESD protection on the inputs can be depicted as shown in Figure 4-1. This structure was chosen to protect the input transistors against many (but not all) over-voltage conditions, and to minimize the input bias current (I_B).

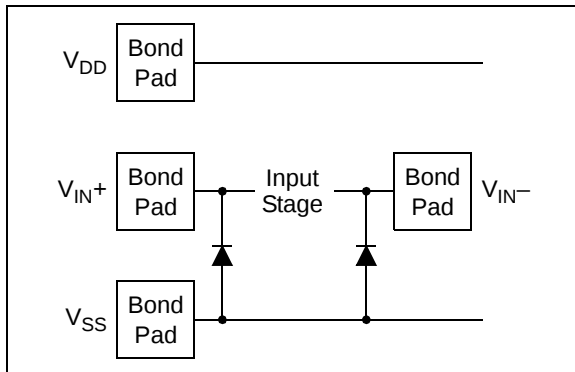


FIGURE 4-1: Simplified Analog Input ESD Structures.

The input ESD diodes clamp the inputs when they try to go more than one diode drop below V_{SS} . They also clamp any voltages that go well above V_{DD} ; their breakdown voltage is high enough to allow normal operation, but not low enough to protect against slow over-voltage (beyond V_{DD}) events. Very fast ESD events (that meet the spec) are limited so that damage does not occur.

In some applications, it may be necessary to prevent excessive voltages from reaching the op amp inputs; Figure 4-2 shows one approach to protecting these inputs.

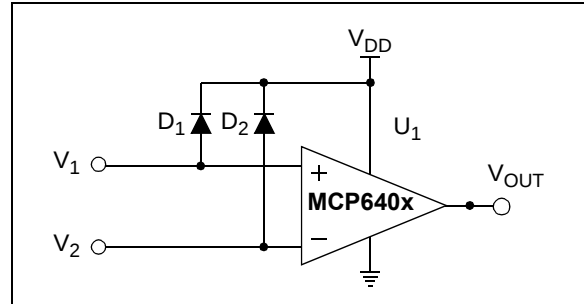


FIGURE 4-2: Protecting the Analog Inputs.

A significant amount of current can flow out of the inputs when the Common Mode voltage (V_{CM}) is below ground (V_{SS}); See Figure 2-32.

4.1.3 INPUT CURRENT LIMITS

In order to prevent damage and/or improper operation of these amplifiers, the circuit must limit the currents into the input pins (see Section 1.1 "Absolute Maximum Ratings †").

Figure 4-3 shows one approach to protecting these inputs. The resistors R_1 and R_2 limit the possible currents in or out of the input pins (and the ESD diodes, D_1 and D_2). The diode currents will go through either V_{DD} or V_{SS} .

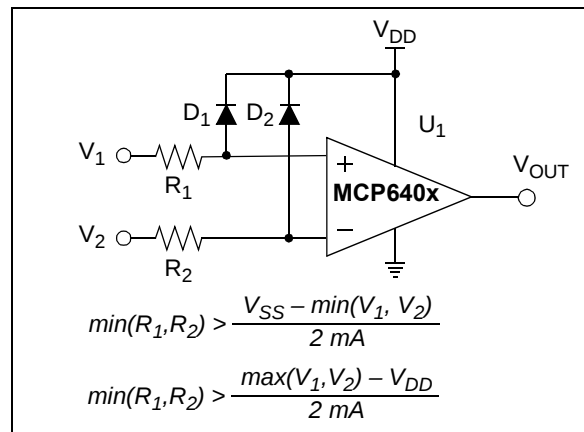


FIGURE 4-3: Protecting the Analog Inputs.

4.1.4 NORMAL OPERATION

The input stage of the MCP6401/1R/1U/2/4 op amps uses two differential input stages in parallel. One operates at a low Common Mode input voltage (V_{CM}), while the other operates at a high V_{CM} . With this topology, the device operates with a V_{CM} up to 300 mV above V_{DD} and 300 mV below V_{SS} . (See Figure 2-11). The input offset voltage is measured at $V_{CM} = V_{SS} - 0.3V$ and $V_{DD} + 0.3V$ to ensure proper operation.

The transition between the input stages occurs when V_{CM} is near $V_{DD} - 1.1V$ (See Figures 2-3 and 2-4). For the best distortion performance and gain linearity, with non-inverting gains, avoid this region of operation.

MCP6401/1R/1U/2/4

4.2 Rail-to-Rail Output

The output voltage range of the MCP6401/1R/1U/2/4 op amps is $V_{SS} + 20$ mV (minimum) and $V_{DD} - 20$ mV (maximum) when $R_L = 10$ k Ω is connected to $V_{DD}/2$ and $V_{DD} = 6.0$ V. Refer to [Figures 2-23](#) and [2-24](#) for more information.

4.3 Capacitive Loads

Driving large capacitive loads can cause stability problems for voltage feedback op amps. As the load capacitance increases, the feedback loop's phase margin decreases and the closed-loop bandwidth is reduced. This produces gain peaking in the frequency response, with overshoot and ringing in the step response. While a unity-gain buffer ($G = +1$ V/V) is the most sensitive to capacitive loads, all gains show the same general behavior.

When driving large capacitive loads with these op amps (e.g., > 100 pF when $G = +1$ V/V), a small series resistor at the output (R_{ISO} in [Figure 4-4](#)) improves the feedback loop's phase margin (stability) by making the output load resistive at higher frequencies. The bandwidth will be generally lower than the bandwidth with no capacitance load.

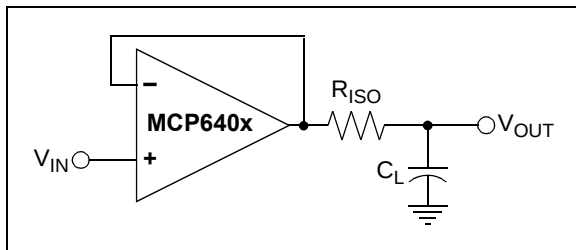


FIGURE 4-4: Output Resistor, R_{ISO} Stabilizes Large Capacitive Loads.

[Figure 4-5](#) gives recommended R_{ISO} values for different capacitive loads and gains. The x-axis is the normalized load capacitance (C_L/G_N), where G_N is the circuit's noise gain. For non-inverting gains, G_N and the Signal Gain are equal. For inverting gains, G_N is $1+|\text{Signal Gain}|$ (e.g., -1 V/V gives $G_N = +2$ V/V).

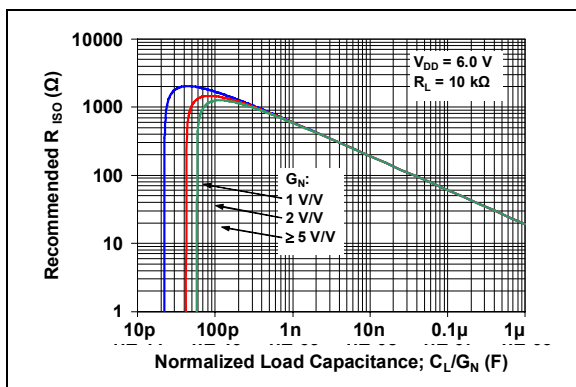


FIGURE 4-5: Recommended R_{ISO} Values for Capacitive Loads.

After selecting R_{ISO} for your circuit, double-check the resulting frequency response peaking and step response overshoot. Modify R_{ISO} 's value until the response is reasonable. Bench evaluation and simulations with the MCP6401/1R/1U/2/4 SPICE macro model are very helpful.

4.4 Supply Bypass

With this family of operational amplifiers, the power supply pin (V_{DD} for single-supply) should have a local bypass capacitor (i.e., 0.01 μ F to 0.1 μ F) within 2 mm for good high frequency performance. It can use a bulk capacitor (i.e., 1 μ F or larger) within 100 mm to provide large, slow currents. This bulk capacitor can be shared with other analog parts.

4.5 Unused Op Amps

An unused op amp in a quad package (MCP6404) should be configured as shown in [Figure 4-6](#). These circuits prevent the output from toggling and causing crosstalk. Circuit A sets the op amp at its minimum noise gain. The resistor divider produces any desired reference voltage within the output voltage range of the op amp; the op amp buffers that reference voltage. Circuit B uses the minimum number of components and operates as a comparator, but it may draw more current.

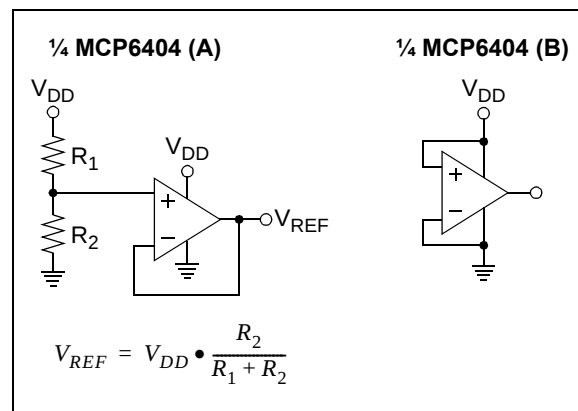


FIGURE 4-6: Unused Op Amps.

4.6 PCB Surface Leakage

In applications where low input bias current is critical, Printed Circuit Board (PCB) surface leakage effects need to be considered. Surface leakage is caused by humidity, dust or other contamination on the board. Under low humidity conditions, a typical resistance between nearby traces is 10^{12} Ω . A 5V difference would cause 5 pA of current to flow; which is greater than the MCP6401/1R/1U/2/4 family's bias current at $+25^\circ\text{C}$ (± 1.0 pA, typical).

The easiest way to reduce surface leakage is to use a guard ring around sensitive pins (or traces). The guard ring is biased at the same voltage as the sensitive pin. An example of this type of layout is shown in Figure 4-7.

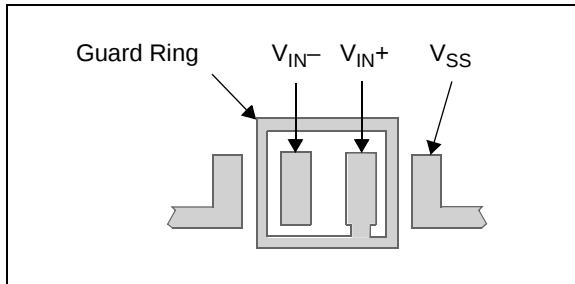


FIGURE 4-7: Example Guard Ring Layout for Inverting Gain.

1. Non-inverting Gain and Unity-Gain Buffer:
 - a) Connect the non-inverting pin (V_{IN+}) to the input with a wire that does not touch the PCB surface.
 - b) Connect the guard ring to the inverting input pin (V_{IN-}). This biases the guard ring to the Common Mode input voltage.
2. Inverting Gain and Transimpedance Gain Amplifiers (convert current to voltage, such as photo detectors):
 - a) Connect the guard ring to the non-inverting input pin (V_{IN+}). This biases the guard ring to the same reference voltage as the op amp (e.g., $V_{DD}/2$ or ground).
 - b) Connect the inverting pin (V_{IN-}) to the input with a wire that does not touch the PCB surface.

4.7 Application Circuits

4.7.1 PRECISION HALF-WAVE RECTIFIER

The precision half-wave rectifier, which is also known as a super diode, is a configuration obtained with an operational amplifier in order to have a circuit behaving like an ideal diode and rectifier. It effectively cancels the forward voltage drop of the diode so that very low level signals can still be rectified with minimal error. This can be useful for high-precision signal processing. The MCP6401/1R/1U/2/4 op amps have high input impedance, low input bias current and rail-to-rail input/output, which makes this device suitable for precision rectifier applications.

Figure 4-8 shows a precision half-wave rectifier and its transfer characteristic. The rectifier's input impedance is determined by the input resistor R_1 . To avoid loading effect, it must be driven from a low impedance source.

When V_{IN} is greater than zero, D_1 is OFF, D_2 is ON, and V_{OUT} is zero. When V_{IN} is less than zero, D_1 is ON, D_2 is OFF, and V_{OUT} is the V_{IN} with an amplification of $-R_2/R_1$.

The rectifier circuit shown in Figure 4-8 has the benefit that the op amp never goes in saturation, so the only thing affecting its frequency response is the amplification and the gain bandwidth product.

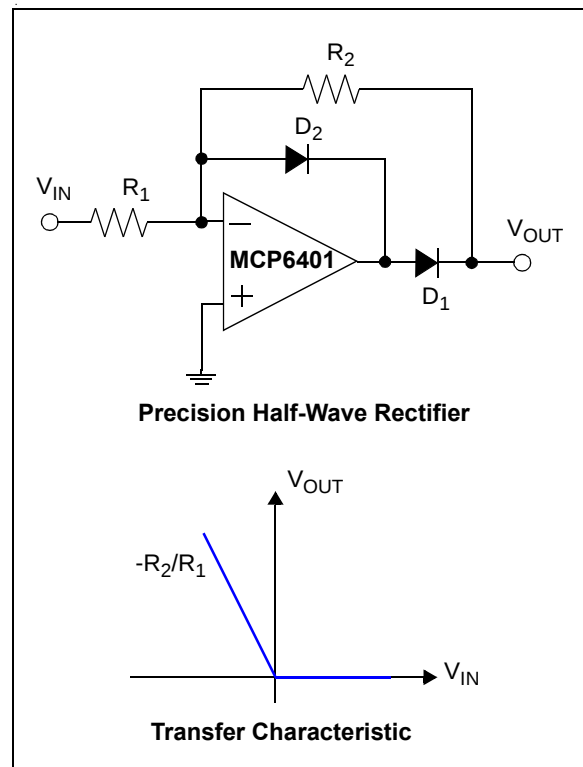


FIGURE 4-8: Precision Half-Wave Rectifier.

MCP6401/1R/1U/2/4

4.7.2 BATTERY CURRENT SENSING

The MCP6401/1R/1U/2/4 op amps' Common Mode Input Range, which goes 0.3V beyond both supply rails, supports their use in high-side and low-side battery current sensing applications. The low quiescent current (45 μ A, typical) helps prolong battery life, and the rail-to-rail output supports detection of low currents.

Figure 4-9 shows a high side battery current sensor circuit. The 10 Ω resistor is sized to minimize power losses. The battery current (I_{DD}) through the 10 Ω resistor causes its top terminal to be more negative than the bottom terminal. This keeps the Common Mode input voltage of the op amp below V_{DD} , which is within its allowed range. The output of the op amp will also be below V_{DD} , which is within its Maximum Output Voltage Swing specification.

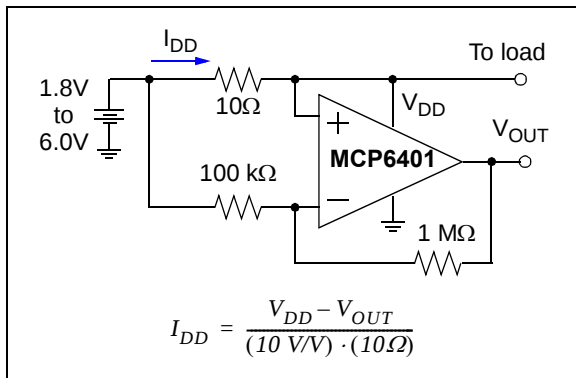


FIGURE 4-9: Supply Current Sensing.

4.7.3 INSTRUMENTATION AMPLIFIER

The MCP6401/1R/1U/2/4 op amps are well suited for conditioning sensor signals in battery-powered applications. Figure 4-10 shows a two op amp instrumentation amplifier, using the MCP6402, that works well for applications requiring rejection of Common Mode noise at higher gains. The reference voltage (V_{REF}) is supplied by a low impedance source. In single supply applications, V_{REF} is typically $V_{DD}/2$.

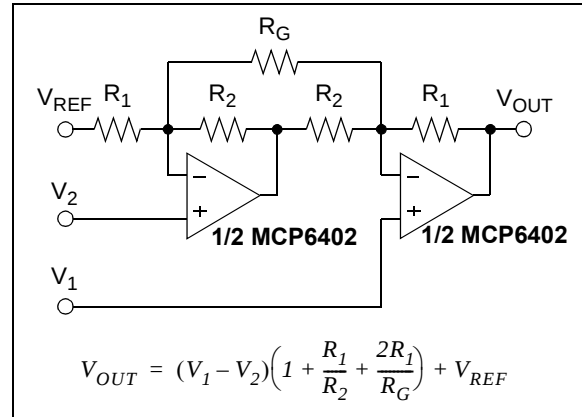


FIGURE 4-10: Two Op Amp Instrumentation Amplifier.

5.0 DESIGN AIDS

Microchip provides the basic design tools needed for the MCP6401/1R/1U/2/4 family of op amps.

5.1 SPICE Macro Model

The latest SPICE macro model for the MCP6401/1R/1U/2/4 op amp is available on the Microchip web site at www.microchip.com. The model was written and tested in official Orcad (Cadence) owned PSPICE. For the other simulators, it may require translation.

The model covers a wide aspect of the op amp's electrical specifications. Not only does the model cover voltage, current, and resistance of the op amp, but it also covers the temperature and noise effects on the behavior of the op amp. The model has not been verified outside of the specification range listed in the op amp data sheet. The model behaviors under these conditions cannot be guaranteed that it will match the actual op amp performance.

Moreover, the model is intended to be an initial design tool. Bench testing is a very important part of any design and cannot be replaced with simulations. Also, simulation results using this macro model need to be validated by comparing them to the data sheet specifications and characteristic curves.

5.2 FilterLab® Software

Microchip's FilterLab® software is an innovative software tool that simplifies analog active filter (using op amps) design. Available at no cost from the Microchip web site at www.microchip.com/filterlab, the FilterLab design tool provides full schematic diagrams of the filter circuit with component values. It also outputs the filter circuit in SPICE format, which can be used with the macro model to simulate actual filter performance.

5.3 Mindi™ Circuit Designer and Simulator

Microchip's Mindi™ Circuit Designer and Simulator aids in the design of various circuits useful for active filter, amplifier and power-management applications. It is a free online circuit designer and simulator available from the Microchip web site at www.microchip.com/mindi. This interactive circuit designer and simulator enables designers to quickly generate circuit diagrams, and simulate circuits. Circuits developed using the Mindi Circuit Designer and Simulator can be downloaded to a personal computer or workstation.

5.4 Microchip Advanced Part Selector (MAPS)

MAPS is a software tool that helps semiconductor professionals efficiently identify Microchip devices that fit a particular design requirement. Available at no cost from the Microchip website at www.microchip.com/maps, the MAPS is an overall selection tool for Microchip's product portfolio that includes Analog, Memory, MCUs and DSCs. Using this tool you can define a filter to sort features for a parametric search of devices and export side-by-side technical comparison reports. Helpful links are also provided for Datasheets, Purchase, and Sampling of Microchip parts.

5.5 Analog Demonstration and Evaluation Boards

Microchip offers a broad spectrum of Analog Demonstration and Evaluation Boards that are designed to help you achieve faster time to market. For a complete listing of these boards and their corresponding user's guides and technical information, visit the Microchip web site at www.microchip.com/analogtools.

Some boards that are especially useful are:

- MCP6XXX Amplifier Evaluation Board 1
- MCP6XXX Amplifier Evaluation Board 2
- MCP6XXX Amplifier Evaluation Board 3
- MCP6XXX Amplifier Evaluation Board 4
- Active Filter Demo Board Kit
- 5/6-Pin SOT-23 Evaluation Board, P/N VSUPEV2
- 8-Pin SOIC/MSOP/TSSOP/DIP Evaluation Board, P/N SOIC8EV
- 14-Pin SOIC/TSSOP/DIP Evaluation Board, P/N SOIC14EV

5.6 Application Notes

The following Microchip Analog Design Note and Application Notes are available on the Microchip web site at www.microchip.com/appnotes and are recommended as supplemental reference resources.

- **ADN003:** *"Select the Right Operational Amplifier for your Filtering Circuits"*, DS21821
- **AN722:** *"Operational Amplifier Topologies and DC Specifications"*, DS00722
- **AN723:** *"Operational Amplifier AC Specifications and Applications"*, DS00723
- **AN884:** *"Driving Capacitive Loads With Op Amps"*, DS00884
- **AN990:** *"Analog Sensor Conditioning Circuits – An Overview"*, DS00990
- **AN1177:** *"Op Amp Precision Design: DC Errors"*, DS01177
- **AN1228:** *"Op Amp Precision Design: Random Noise"*, DS01228
- **AN1297:** *"Microchip's Op Amp SPICE Macro Models"*, DS01297

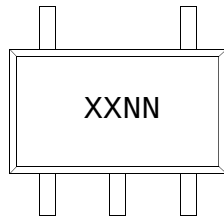
These application notes and others are listed in the design guide:

- *"Signal Chain Design Guide"*, DS21825

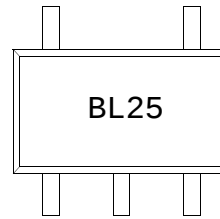
6.0 PACKAGING INFORMATION

6.1 Package Marking Information

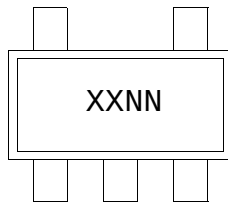
5-Lead SC70 (MCP6401 only)



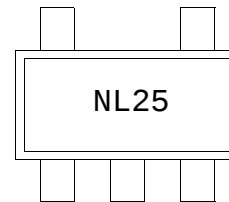
Example:



5-Lead SOT-23

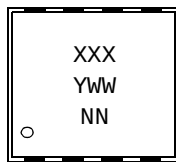


Example:

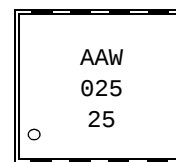


Part Number	Code
MCP6401T-E/OT	NLNN
MCP6401RT-E/OT	NMNN
MCP6401UT-E/OT	NPNN

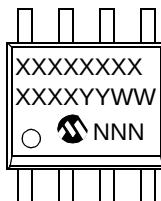
8-Lead TDFN (2 x 3)



Example:



8-Lead SOIC (150 mil)



Example:



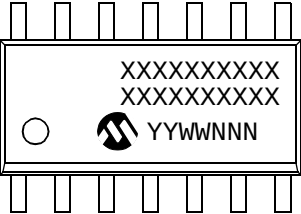
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

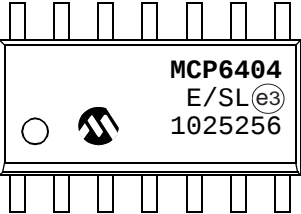
MCP6401/1R/1U/2/4

Package Marking Information (Continued)

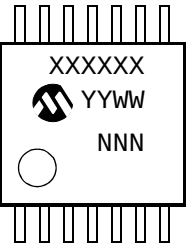
14-Lead SOIC (150 mil) (MCP6404)



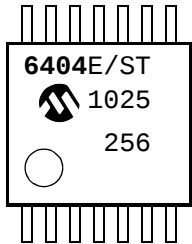
Example:



14-Lead TSSOP (MCP6404)



Example:

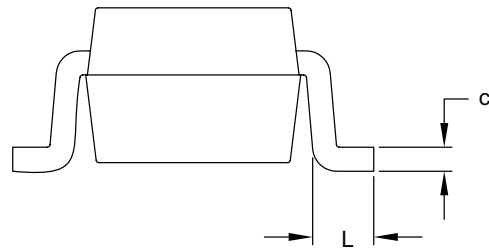
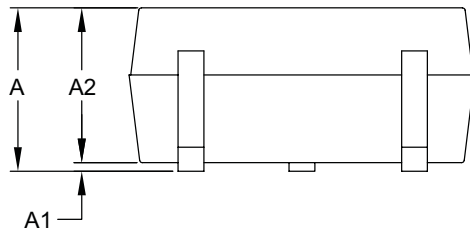
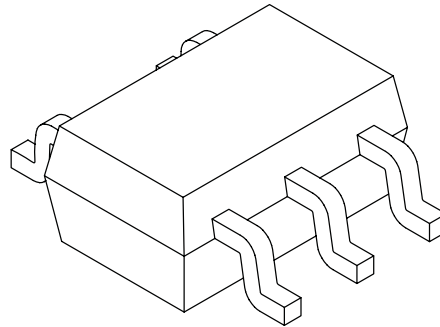
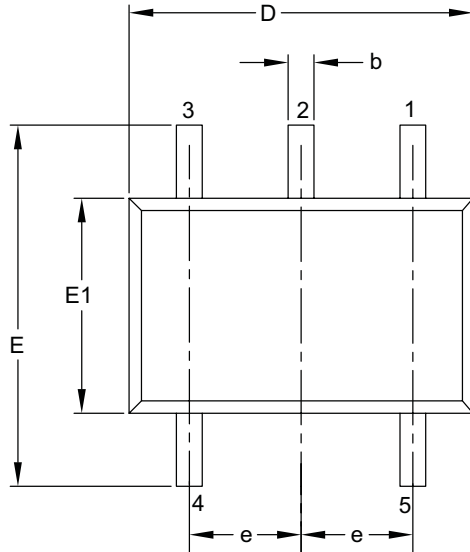


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

5-Lead Plastic Small Outline Transistor (LT) [SC70]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		5		
Pitch	e		0.65 BSC		
Overall Height	A		0.80	–	1.10
Molded Package Thickness	A2		0.80	–	1.00
Standoff	A1		0.00	–	0.10
Overall Width	E		1.80	2.10	2.40
Molded Package Width	E1		1.15	1.25	1.35
Overall Length	D		1.80	2.00	2.25
Foot Length	L		0.10	0.20	0.46
Lead Thickness	c		0.08	–	0.26
Lead Width	b		0.15	–	0.40

Notes:

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

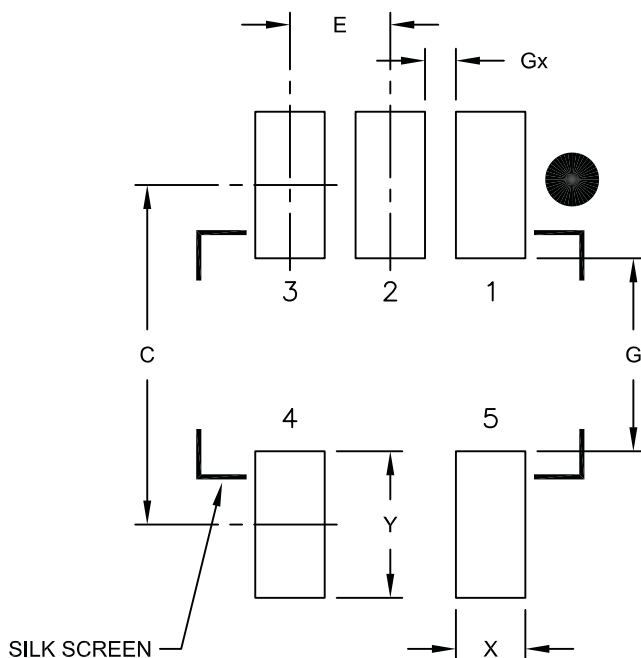
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-061B

MCP6401/1R/1U/2/4

5-Lead Plastic Small Outline Transistor (LT) [SC70]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		2.20	
Contact Pad Width	X			0.45
Contact Pad Length	Y			0.95
Distance Between Pads	G	1.25		
Distance Between Pads	Gx	0.20		

Notes:

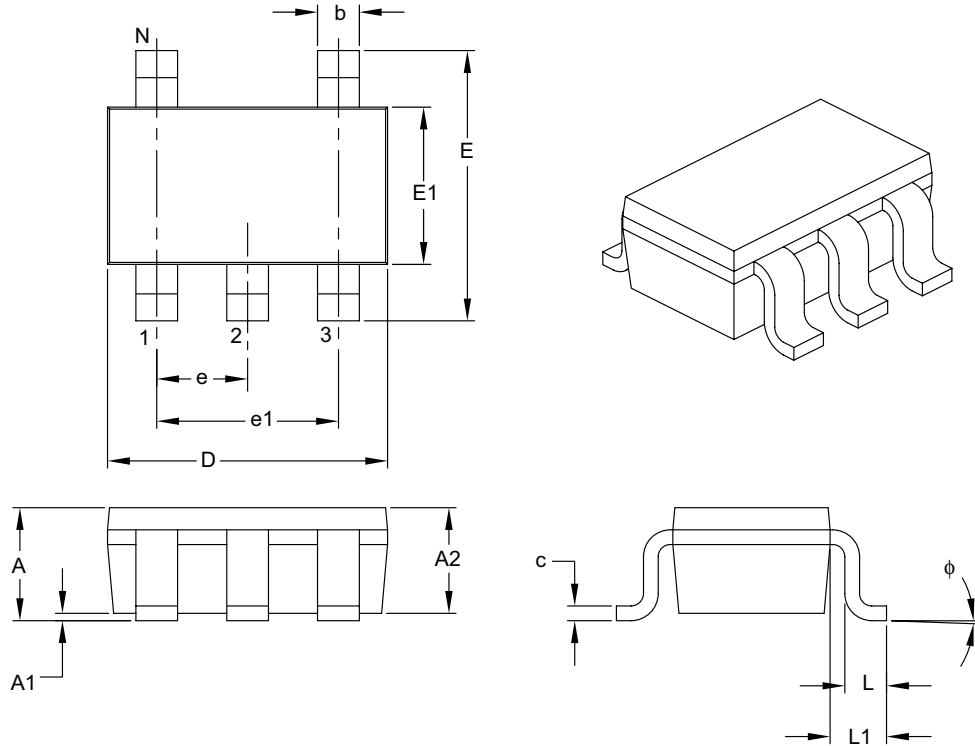
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2061A

5-Lead Plastic Small Outline Transistor (OT) [SOT-23]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	5		
Lead Pitch	e	0.95 BSC		
Outside Lead Pitch	e1	1.90 BSC		
Overall Height	A	0.90	—	1.45
Molded Package Thickness	A2	0.89	—	1.30
Standoff	A1	0.00	—	0.15
Overall Width	E	2.20	—	3.20
Molded Package Width	E1	1.30	—	1.80
Overall Length	D	2.70	—	3.10
Foot Length	L	0.10	—	0.60
Footprint	L1	0.35	—	0.80
Foot Angle	φ	0°	—	30°
Lead Thickness	c	0.08	—	0.26
Lead Width	b	0.20	—	0.51

Notes:

- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.127 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

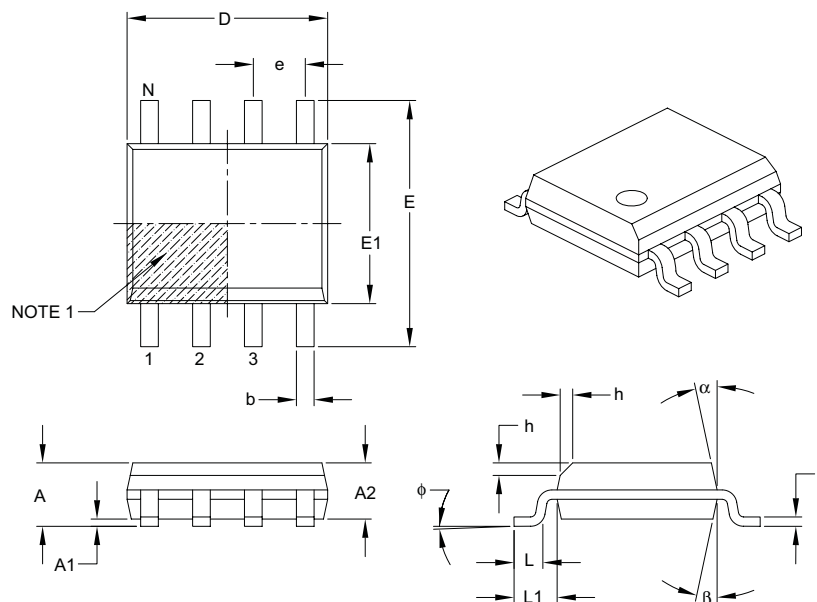
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-091B

MCP6401/1R/1U/2/4

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		1.27 BSC		
Overall Height	A		–	–	1.75
Molded Package Thickness	A2		1.25	–	–
Standoff §	A1		0.10	–	0.25
Overall Width	E		6.00 BSC		
Molded Package Width	E1		3.90 BSC		
Overall Length	D		4.90 BSC		
Chamfer (optional)	h		0.25	–	0.50
Foot Length	L		0.40	–	1.27
Footprint	L1		1.04 REF		
Foot Angle	φ		0°	–	8°
Lead Thickness	c		0.17	–	0.25
Lead Width	b		0.31	–	0.51
Mold Draft Angle Top	α		5°	–	15°
Mold Draft Angle Bottom	β		5°	–	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

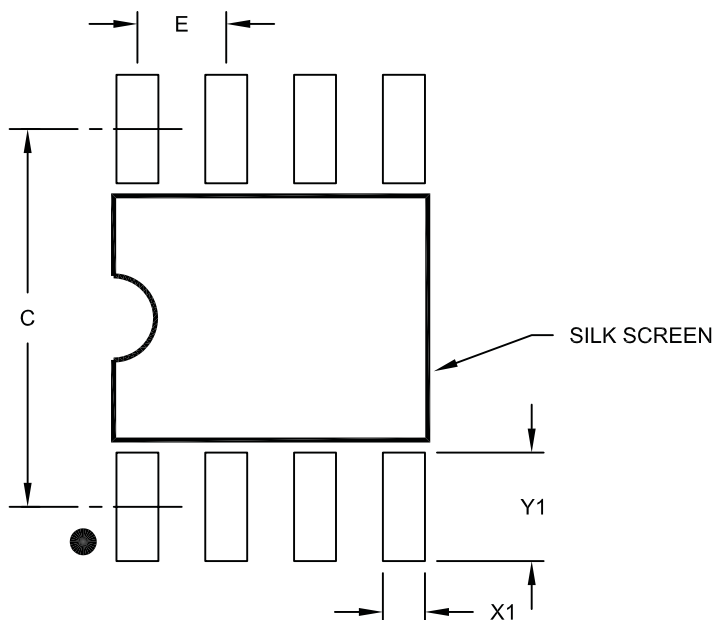
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-057B

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

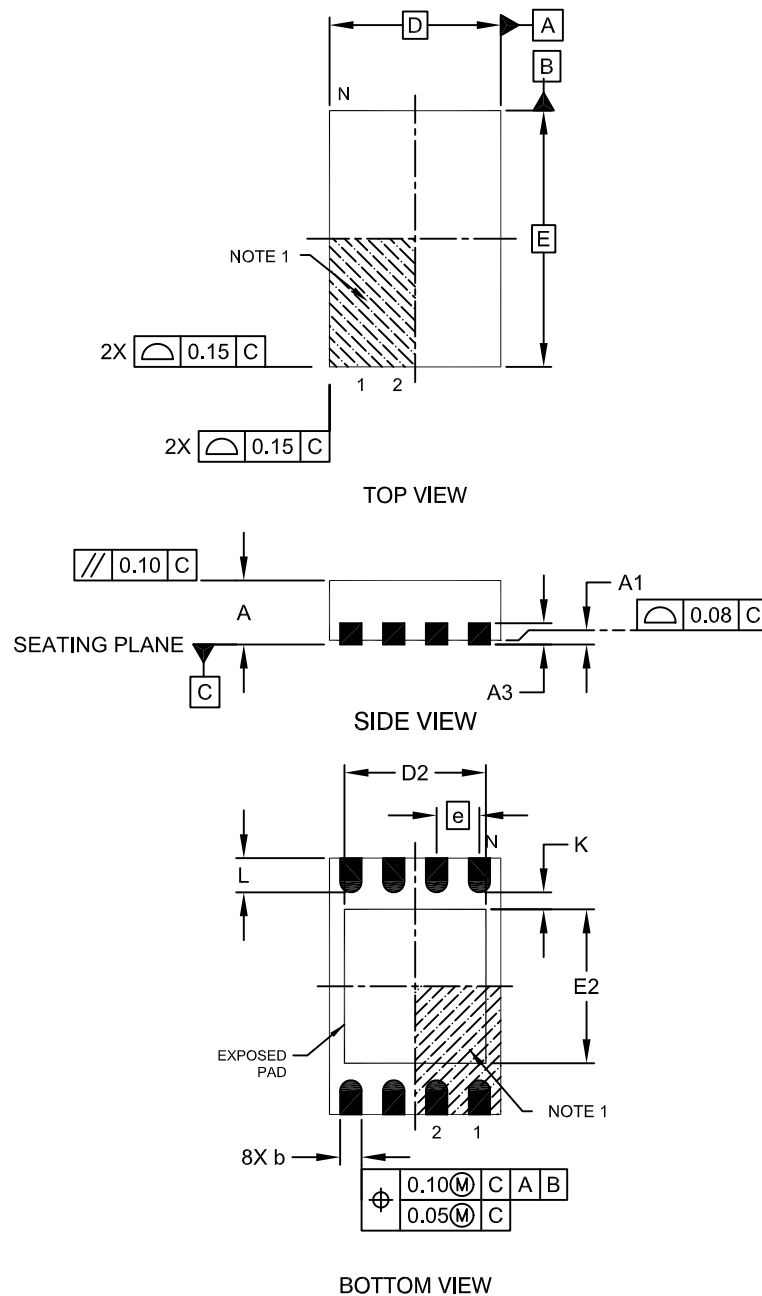
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

MCP6401/1R/1U/2/4

8-Lead Plastic Dual Flat, No Lead Package (MN) – 2x3x0.75mm Body [TDFN]

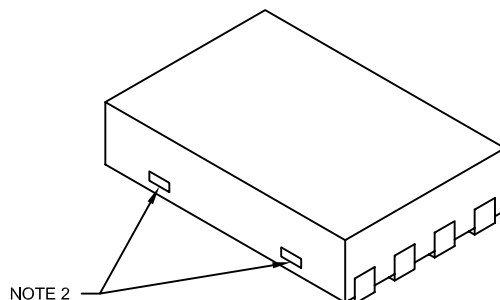
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



MCP6401/1R/1U/2/4

8-Lead Plastic Dual Flat, No Lead Package (MN) – 2x3x0.75mm Body [TDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Pins	N		8		
Pitch	e		0.50 BSC		
Overall Height	A		0.70	0.75	0.80
Standoff	A1		0.00	0.02	0.05
Contact Thickness	A3		0.20 REF		
Overall Length	D		2.00 BSC		
Overall Width	E		3.00 BSC		
Exposed Pad Length	D2		1.20	-	1.60
Exposed Pad Width	E2		1.20	-	1.60
Contact Width	b		0.20	0.25	0.30
Contact Length	L		0.25	0.30	0.45
Contact-to-Exposed Pad	K		0.20	-	-

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package may have one or more exposed tie bars at ends.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

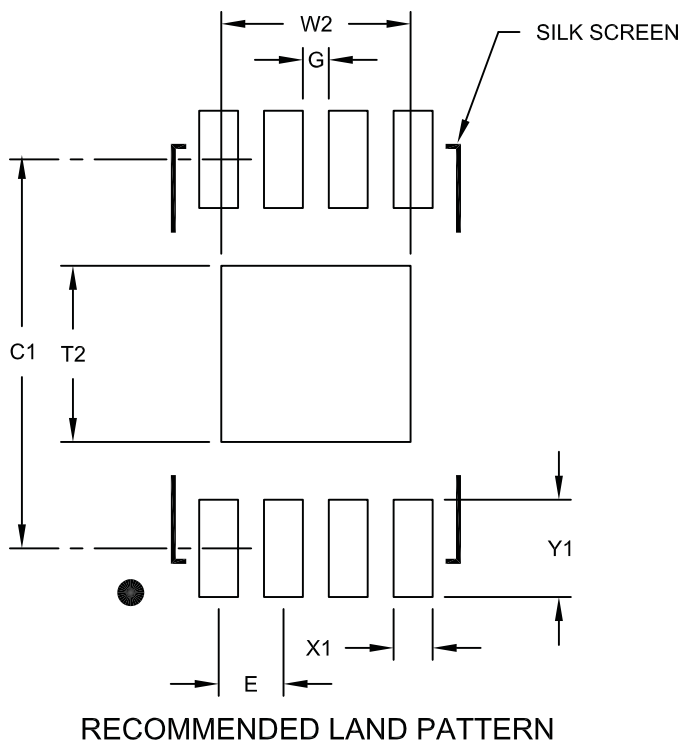
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-129C

MCP6401/1R/1U/2/4

8-Lead Plastic Dual Flat, No Lead Package (MN) – 2x3x0.75 mm Body [TDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Optional Center Pad Width	W2			1.46
Optional Center Pad Length	T2			1.36
Contact Pad Spacing	C1		3.00	
Contact Pad Width (X8)	X1			0.30
Contact Pad Length (X8)	Y1			0.75
Distance Between Pads	G	0.20		

Notes:

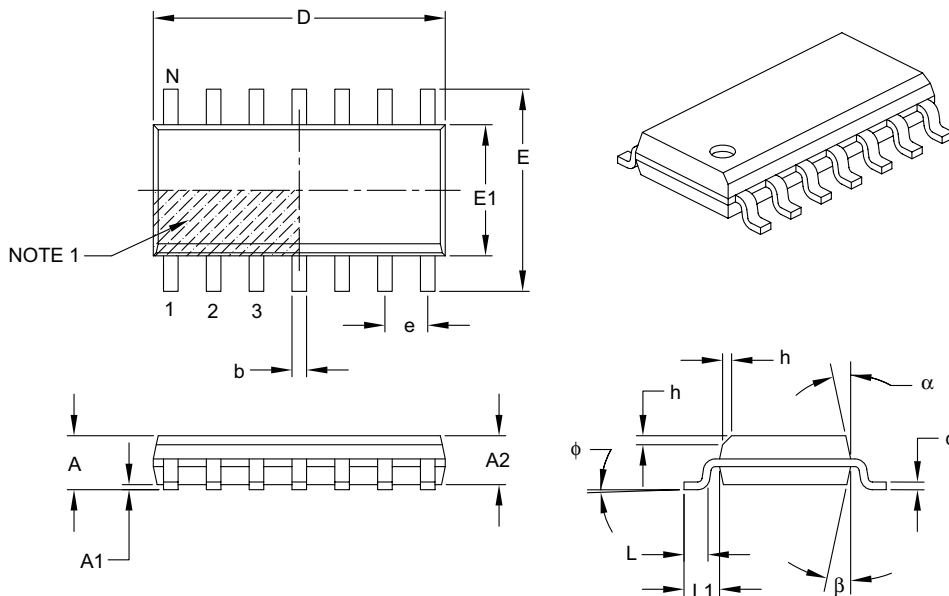
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2129A

14-Lead Plastic Small Outline (SL) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	14		
Pitch	e	1.27 BSC		
Overall Height	A	–	–	1.75
Molded Package Thickness	A2	1.25	–	–
Standoff §	A1	0.10	–	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	8.65 BSC		
Chamfer (optional)	h	0.25	–	0.50
Foot Length	L	0.40	–	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	–	8°
Lead Thickness	c	0.17	–	0.25
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

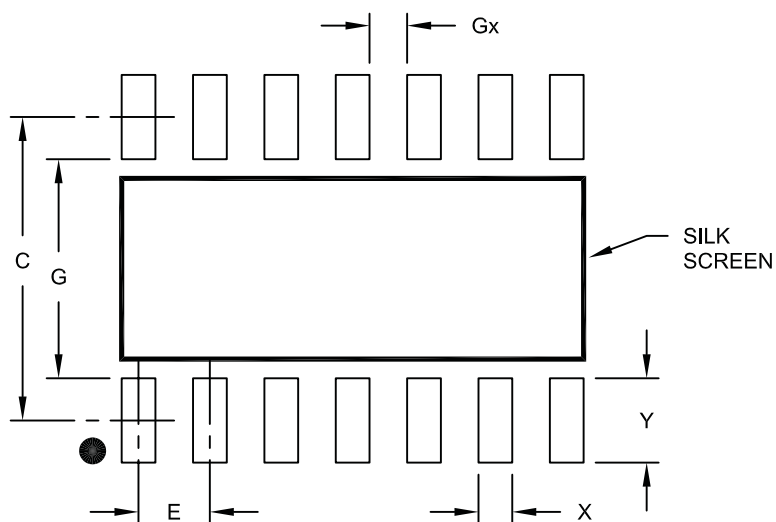
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-065B

MCP6401/1R/1U/2/4

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width	X			0.60
Contact Pad Length	Y			1.50
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	3.90		

Notes:

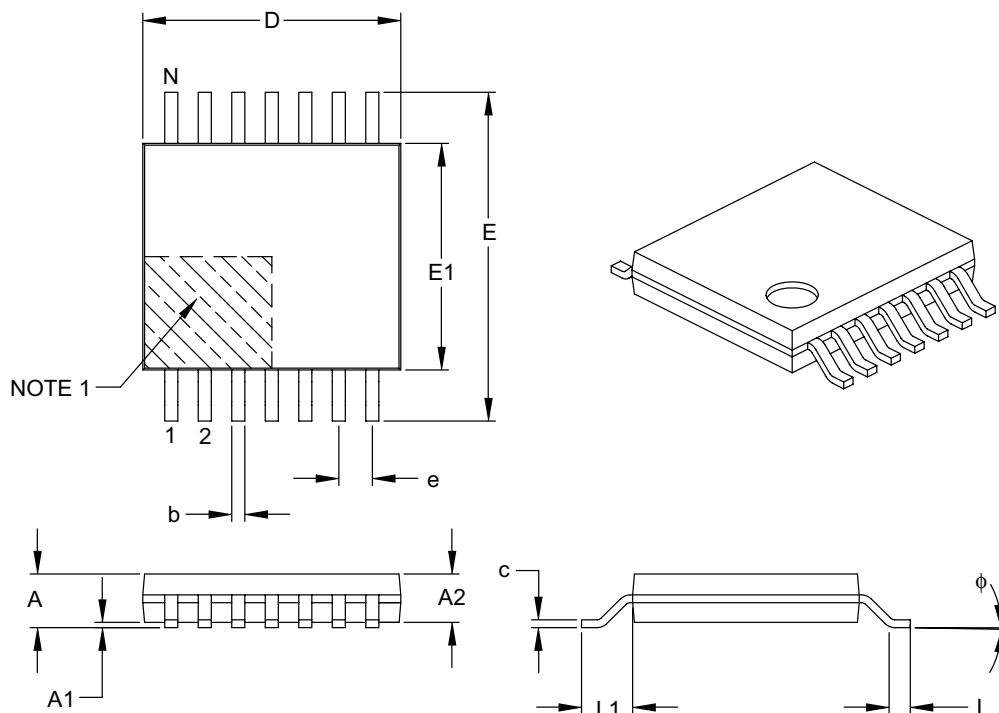
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2065A

14-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	14		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	–	0.15
Overall Width	E	6.40 BSC		
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	–	8°
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.19	–	0.30

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

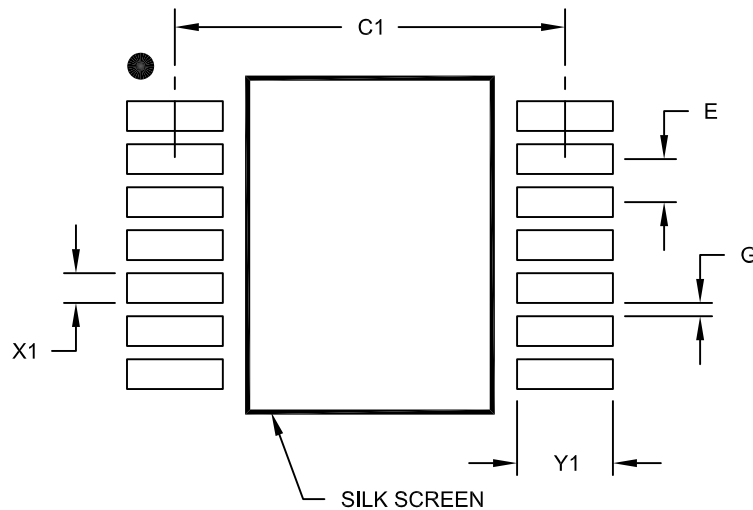
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-087B

MCP6401/1R/1U/2/4

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C1		5.90	
Contact Pad Width (X14)	X1			0.45
Contact Pad Length (X14)	Y1			1.45
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2087A

APPENDIX A: REVISION HISTORY

Revision B (June 2010)

The following is the list of modifications:

1. Added the MCP6402 and MCP6404 package information.
2. Updated the ESD protection value on all pins in **Section 1.1 “Absolute Maximum Ratings †”**.
3. Added [Figure 2-33](#).
4. Updated [Table 3-1](#).
5. Updated **Section 4.1.2 “Input Voltage Limits”**.
6. Added **Section 4.1.3 “Input Current Limits”**.
7. Added **Section 4.5 “Unused Op Amps”**.
8. Updated **Section 5.5 “Analog Demonstration and Evaluation Boards”**.
9. Updated the package markings information and drawings.
10. Updated the Product Identification System page.

Revision A (December 2009)

- Original Release of this Document.

MCP6401/1R/1U/2/4

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>-X</u>	<u>/XX</u>	Examples:
Device	Temperature Range	Package	
Device:	MCP6401T:	Single Op Amp (Tape and Reel) (SC70, SOT-23)	a) MCP6401T-E/LT: Tape and Reel, 5LD SC70 pkg
	MCP6401RT:	Single Op Amp (Tape and Reel) (SOT-23)	b) MCP6401T-E/OT: Tape and Reel, 5LD SOT-23 pkg
	MCP6401UT:	Single Op Amp (Tape and Reel) (SOT-23)	c) MCP6401RT-E/OT: Tape and Reel, 5LD SOT-23 pkg
	MCP6402:	Dual Op Amp	d) MCP6401UT-E/OT: Tape and Reel, 5LD SOT-23 pkg
	MCP6402T:	Dual Op Amp (Tape and Reel) (SOIC, 2x3 TDFN)	e) MCP6402-E/SN: 8LD SOIC pkg
	MCP6404:	Quad Op Amp	f) MCP6402T-E/SN: Tape and Reel, 8LD SOIC pkg
	MCP6404T:	Quad Op Amp (Tape and Reel) (SOIC, TSSOP)	g) MCP6402T-E/MNY: Tape and Reel, 8LD 2x3 TDFN pkg
Temperature Range:	E	= -40°C to +125°C	h) MCP6404-E/SL: 14LD SOIC pkg
Package:	LT	= Plastic Package (SC70), 5-lead	i) MCP6404T-E/SL: Tape and Reel, 14LD SOIC pkg
	OT	= Plastic Small Outline Transistor (SOT-23), 5-lead	j) MCP6404-E/ST: 14LD TSSOP pkg
	SN	= Plastic SOIC, (3.90 mm body), 8-lead	k) MCP6404T-E/ST: Tape and Reel, 14LD TSSOP pkg.
	MNY*	= Plastic Dual Flat, No Lead, (2x3 TDFN), 8-lead	
	SL	= Plastic SOIC (3.90 mm body), 14-lead	
	ST	= Plastic TSSOP (4.4mm body), 14-lead	
	* Y	= Nickel palladium gold manufacturing designator. Only available on the TDFN package.	

MCP6401/1R/1U/2/4

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Octopus, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, PIC³² logo, REAL ICE, rLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2010, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

ISBN: 978-1-60932-338-7

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949:2002 ==

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



WORLDWIDE SALES AND SERVICE

AMERICAS

Corporate Office

2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://support.microchip.com>
Web Address:
www.microchip.com

Atlanta

Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Boston

Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago

Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland

Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas

Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit

Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Kokomo

Kokomo, IN
Tel: 765-864-8360
Fax: 765-864-8387

Los Angeles

Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

Santa Clara

Santa Clara, CA
Tel: 408-961-6444
Fax: 408-961-6445

Toronto

Mississauga, Ontario,
Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2401-1200
Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8528-2100
Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hong Kong SAR

Tel: 852-2401-1200
Fax: 852-2401-3431

China - Nanjing

Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao

Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660
Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Yokohama

Tel: 81-45-471- 6166
Fax: 81-45-471-6122

Korea - Daegu

Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-6578-300
Fax: 886-3-6578-370

Taiwan - Kaohsiung

Tel: 886-7-536-4818
Fax: 886-7-536-4803

Taiwan - Taipei

Tel: 886-2-2500-6610
Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid

Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

UK - Wokingham

Tel: 44-118-921-5869
Fax: 44-118-921-5820

01/05/10